

a capacitatively coupled discharge means consisting of mutually isolated multiple conductors; and

an electromagnetic wave radiating means to cause radio frequency displacement current to flow between said conductors and to emit electromagnetic wave;

C1 wherein said electromagnetic wave radiating means further comprises a radiated electromagnetic wave power control means to control radiated electromagnetic wave power using the radio frequency displacement current control means forming a resonant circuit.

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3. (amended) A plasma processing apparatus according to Claim 1 or 2 further characterized by a means to store a processing procedure to control distribution during plasma processing and a means to control plasma distribution according to the processing procedure stored in said store means.

7. (amended) A plasma processing apparatus to provide plasma processing of a substrate by plasma, comprising:

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a plasma processing gas supply means,
an exhaust means in a plasma process chamber,
a plasma generating means, and
a means to send RF current to the substrate to be processed,

wherein said plasma processing apparatus further includes a RF bias circuit which is floated with respect to ground so as to send RF current to the substrate to be processed .

8. (amended) A plasma processing apparatus to provide plasma processing of a substrate by plasma, comprising:

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at
a plasma processing gas supply means,
an exhaust means in a plasma process chamber,
a plasma generating means,
a means to process plasma using the generated plasma;
said means to send RF current to the substrate to be processed further
characterized in that;
multiple RF current conducting means are installed at a position opposite to a
position where the substrate to be processed is mounted, and
said multiple RF current conducting means are provided with a means to
control a ratio of RF current flowing from the substrate to be processed to each of
the RF current conducting means.

REMARKS

By the above amendment, the specification has been amended to utilize alternative acceptable language to describe the present invention so as to provide clear antecedent basis for the claimed features. Additionally, claims 1-3, 7 and 8 have been amended to correct minor informalities and to clarify features of the present invention.

At the outset, as to the Examiner's indication that the Substitute Specification filed November 29, 2001 has not been entered and that a marked up version is not provided, applicants submit that apparently the marked up version has been misplaced by the U.S. Patent and Trademark Office. Enclosed, please find a copy of the postcard receipt of the papers filed November 29, 2001, indicating receipt of "Substitute Specification & Marked Up Copy of Original Specification & Abstract". Thus, a marked up copy was submitted on November 29, 2001, the receipt thereof being evidenced by the postcard receipt. Submitted herewith is another copy of the